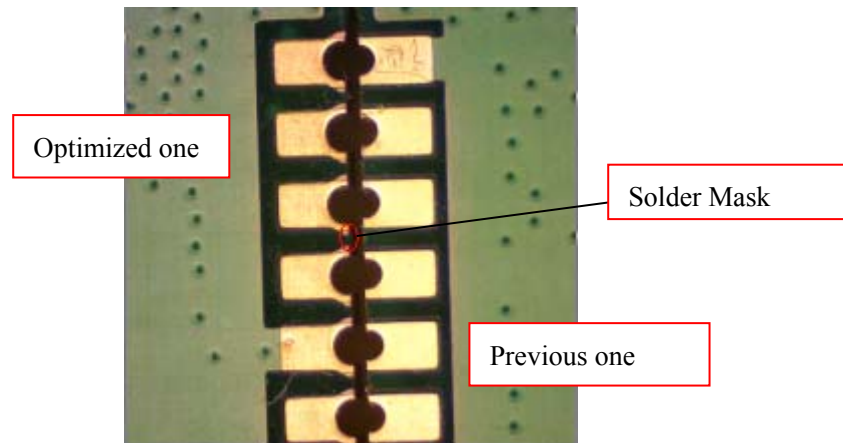


Subject	SIM900 optimize the soldering PAD
Original soldering PAD	Refer to Figure 3 of SIM900_Hardware Design_V2.03
Optimized soldering PAD	Refer to Figure 3 of SIM900_Hardware Design_V2.04
Classification	<input type="checkbox"/> Design Change <input checked="" type="checkbox"/> Manufacturing process/method <input type="checkbox"/> Manufacturing condition <input type="checkbox"/> Manufacturing location <input type="checkbox"/> Material <input type="checkbox"/> Others
Effective D/C of PCB	Since 1245

Reasons for Change

The comparison between previous one and optimized one is detailed in the following figure.



Some factors contribute to our optimizing the soldering PAD of SIM900 module are summarized as follows. One is to improve the efficiency of PCB production. The other one is to improve the solderability, the soldering can climb to the side or top of the castle hole more smoothly with the optimized soldering PAD.

Although the diameter of castle hole is slightly enlarged, the excessive part has been coated with solder mask to avoid the Solder Short risk. Moreover, it has been verified internally in SIMCom that this modification will not affect production process of SIM900 in the client side at all.

Please contact us if you have any question.

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